

Switch-mode Power Rectifier MBRB20100CTG, NRVBB20100CTT4G, NRVBBS20100CTT4G

D²PAK Surface Mount Power Package

The D²PAK Power Rectifier is a state-of-the-art device that employs the use of the Schottky Barrier principle with a platinum barrier metal.

Features

- Package Designed for Power Surface Mount Applications
- Center-Tap Configuration
- Guardring for Stress Protection
- Low Forward Voltage
- 175 °C Operating Junction Temperature
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Short Heat Sink Tab Manufactured-Not Sheared!
- Similar in Size to Industry Standard TO-220 Package
- NRVBB and NRVBBS Prefixes for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant*

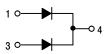
Mechanical Characteristics

- Case: Epoxy, Molded, Epoxy Meets UL 94 V-0
- Weight: 1.4 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260 °C Max. for 10 Seconds
- MBRB20100CTG, NRVBB20100CTT4G Meets MSL1 Requirements
- NRVBBS20100CTT4G Meets MSL2 Requirements
- ESD Ratings:
 - ♦ Machine Model = C (> 400 V)
 - ♦ Human Body Model = 3B (> 8000 V)

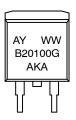
SCHOTTKY BARRIER RECTIFIER 20 AMPERES 100 VOLTS



D²PAK CASE 418B STYLE 3



MARKING DIAGRAM



A = Assembly Location

Y = Year

WW = Work Week

B20100 = Device Code

G = Pb-Free Package

AKA = Diode Polarity

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

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^{*}For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, <u>SOLDERRM/D</u>

MBRB20100CTG, NRVBB20100CTT4G, NRVBBS20100CTT4G

MAXIMUM RATINGS (Per Leg)

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	100	V
Average Rectified Forward Current Per Leg (Rated V_R , T_C = 155 °C) Total Device	I _{F(AV)}	10 20	Α
Peak Repetitive Forward Current (Rated V _R , Square Wave, 20 kHz, T _C = 150 °C)	IFRM	20	Α
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	150	Α
Peak Repetitive Reverse Surge Current (2.0 µs, 1.0 kHz)	I _{RRM}	0.5	Α
Storage Temperature Range	T _{stg}	-65 to +175	°C
Operating Junction Temperature (Note 1)	T _J	-65 to +175	°C
Voltage Rate of Change (Rated V _R)	dv/dt	10,000	V/μs

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS (Per Leg)

Characteristic	Symbol	Value	Unit
Thermal Resistance,			°C/W
Junction-to-Case	$R_{\theta JC}$	2.0	
Junction-to-Ambient (Note 2)	$R_{ hetaJA}$	50	

^{2.} When mounted using minimum recommended pad size on FR-4 board.

ELECTRICAL CHARACTERISTICS (Per Leg)

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 3) ($i_F = 10$ Amp, $T_C = 125$ °C) ($i_F = 10$ Amp, $T_C = 25$ °C) ($i_F = 20$ Amp, $T_C = 125$ °C) ($i_F = 20$ Amp, $T_C = 25$ °C)	VF	0.75 0.85 0.85 0.95	V
Maximum Instantaneous Reverse Current (Note 3) (Rated dc Voltage, T _J = 125 °C) (Rated dc Voltage, T _J = 25 °C)	i _R	6.0 0.1	mA

^{3.} Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2.0%.

ORDERING INFORMATION

Device	Package	Shipping [†]
MBRB20100CTT4G	D ² PAK (Pb-Free)	800 Units / Tape & Reel
NRVBB20100CTT4G	D ² PAK (Pb-Free)	800 Units / Tape & Reel
NRVBBS20100CTT4G	D ² PAK (Pb-Free)	800 Units / Tape & Reel

DISCONTINUED (Note 4)

Device	Package	Shipping [†]
MBRB20100CTG	D ² PAK (Pb-Free)	50 Units / Rail

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{1.} The heat generated must be less than the thermal conductivity from Junction-to-Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.

^{4.} **DISCONTINUED:** This device is not recommended for new design. Please contact your **onsemi** representative for information. The most current information on this device may be available on www.onsemi.com.

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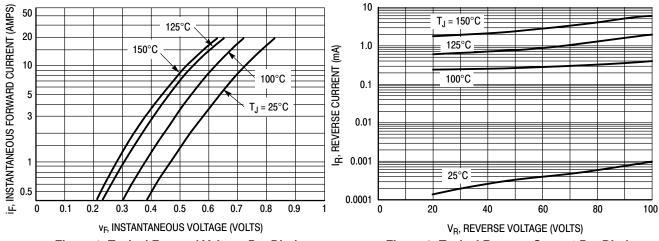


Figure 1. Typical Forward Voltage Per Diode

Figure 2. Typical Reverse Current Per Diode

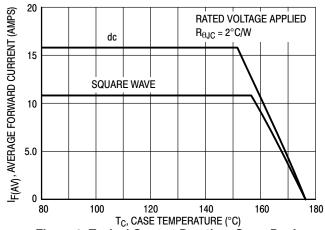


Figure 3. Typical Current Derating, Case, Per Leg

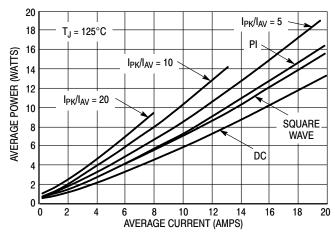


Figure 4. Average Power Dissipation & Average Current

MBRB20100CTG, NRVBB20100CTT4G, NRVBBS20100CTT4G

REVISION HISTORY

Revision	Description of Changes	Date
11	MBRB20100CTG OPN Marked as Discontinued + Rebranded the Data Sheet to onsemi format	7/2/2025

This document has undergone updates prior to the inclusion of this revision history table. The changes tracked here only reflect updates made on the noted approval dates.

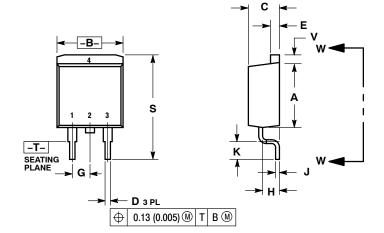




D²PAK 3 CASE 418B-04 **ISSUE L**

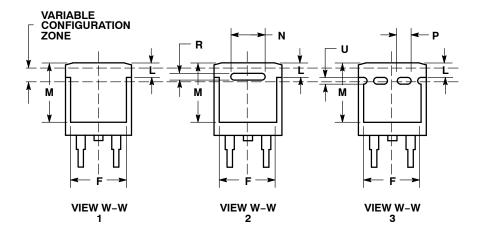
DATE 17 FEB 2015

SCALE 1:1



- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
- 3. 418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.340	0.380	8.64	9.65
В	0.380	0.405	9.65	10.29
C	0.160	0.190	4.06	4.83
D	0.020	0.035	0.51	0.89
E	0.045	0.055	1.14	1.40
F	0.310	0.350	7.87	8.89
G	0.100 BSC		2.54 BSC	
Н	0.080	0.110	2.03	2.79
J	0.018	0.025	0.46	0.64
K	0.090	0.110	2.29	2.79
L	0.052	0.072	1.32	1.83
M	0.280	0.320	7.11	8.13
N	0.197 REF		5.00 REF	
P	0.079 REF		2.00 REF	
R	0.039 REF		0.99 REF	
S	0.575	0.625	14.60	15.88
V	0.045	0.055	1.14	1.40



STYLE 1: PIN 1. BASE 2. COLLECTOR
3. EMITTER
4. COLLECTOR STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN STYLE 3:

STYLE 4: PIN 1. ANODE 2. CATHODE 3. ANODE 4. CATHODE

PIN 1. GATE 2. COLLECTOR 3. EMITTER

4. COLLECTOR

STYLE 5: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. ANODE

STYLE 6: PIN 1. NO CONNECT 2. CATHODE 3. ANODE

4. CATHODE

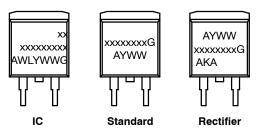
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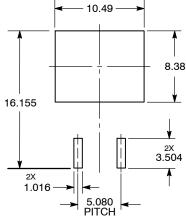
GENERIC MARKING DIAGRAM*



xx = Specific Device Code A = Assembly Location

WL = Wafer Lot
Y = Year
WW = Work Week
G = Pb-Free Package
AKA = Polarity Indicator

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

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^{*}This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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